

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	inspect\$3 near5 semiconductor and product near2 name and design near2 database and process\$3 and revis \$3 near5 inspection near5 conditions	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:04
L2	0	inspect\$3 near5 semiconductor and name and design near2 database and process\$3 and revis\$3 near5 inspection near5 conditions	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:04
L3	0	inspect\$3 near5 semiconductor and name and design near2 database and process\$3 and revis\$3 near5 inspection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:04
L4	0	inspect\$3 near5 semiconductor near2 device and design near2 database and process\$3 and revis\$3 near5 inspection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:05

L5	0	inspect\$3 and semiconductor near2 device and design near2 database and process\$3 and revis\$3 near5 inspection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:05
L6	1	inspect\$3 and semiconductor near2 device and design near5 database and process\$3 and revis\$3 near5 inspection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:05
L7	0	inspect\$3 and semiconductor near2 device and design and access43 and database and process\$3 and revis \$3 near5 inspection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:08
L8	0	inspect\$3 and semiconductor near2 device and design and access43 and database and process\$3 and revis \$3 and inspection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:08
L9	0	inspect\$3 and semiconductor and design and access43 and database and process\$3 and revis\$3 and inspection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:09

L10	425	inspect\$3 and semiconductor and design and database and process\$3 and revis \$3 and inspection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:09
L11	690	438/10.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:09
L12	174	438/11.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:10
L13	126	438/12.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:10
L14	2550	438/14.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:10
L15	4071	438/17.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:11

L16	681	438/18.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:11
L17	60	10 and @pd<="20010724"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:13
L18	155	inspect\$3 and semiconductor and design and database and process\$3 and revis \$3 and inspection and transparent	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:22
L19	28	inspect\$3 and semiconductor and design and database and process\$3 and revis \$3 and inspection and transparent near2 (film or layer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:22
L20	1273	438/16.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:33

L21	11	20 and inspect\$3 and database and transparent near2 (film or layer) and defect\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:34
L22	269	inspect\$3 and database and transparent near2 (film or layer) and defect\$1 and (semiconductor or wafer or substrate)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:35
L23	423	356/239.1.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:49
L24	74	356/239.8.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:50
L25	491	702/84.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:50
L26	131	702/109.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:50

L27	1735	257/e21.521.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:50
L28	239	257/e21.531.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/08/29 15:50

8/29/07 3:51:30 PM

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